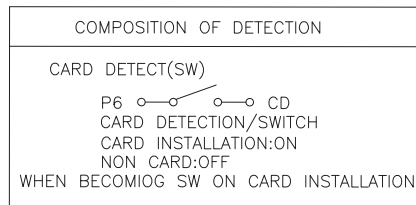
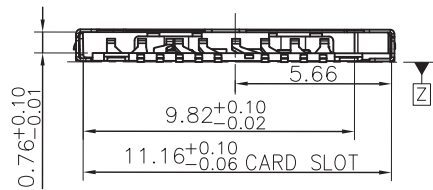
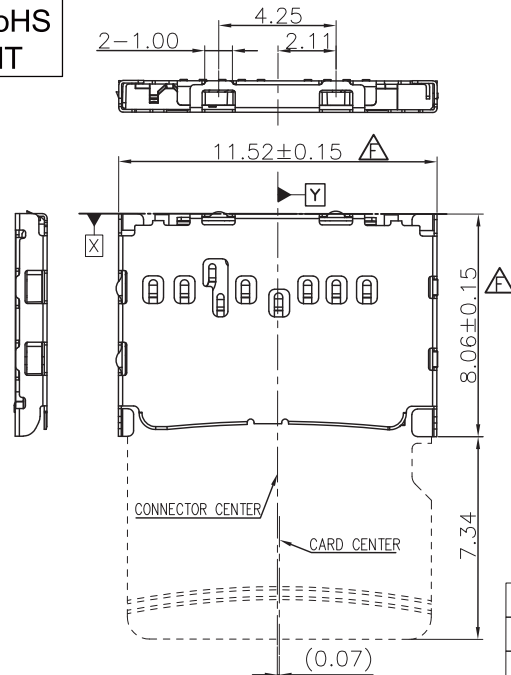
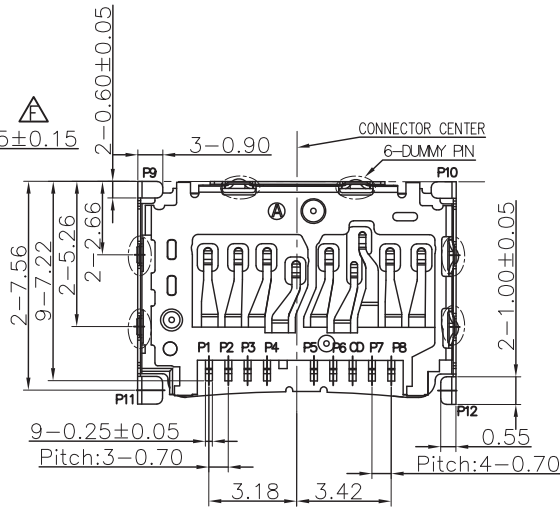


REACH & RoHS
COMPLIANT

* 所有原料材质, 生产制程, 电镀必须符合HF要求

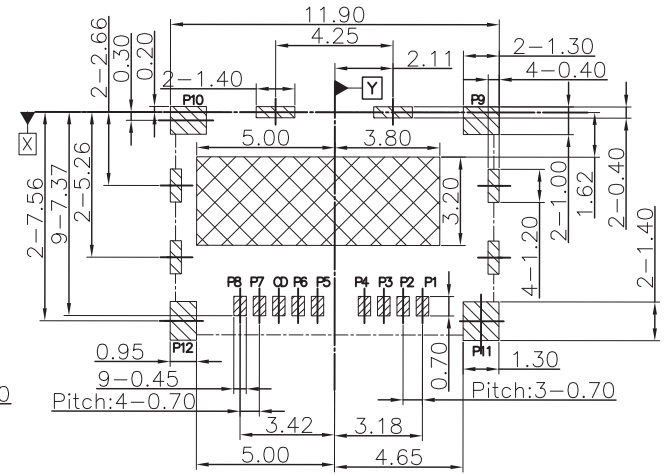


Pin Define	
P1	DAT2
P2	CD/DAT3
P3	CMD
P4	VDD
P5	CLK
P6	VSS
CD	CARD DETECT
P7	DAT0
P8	DAT1
P9-P12	GND

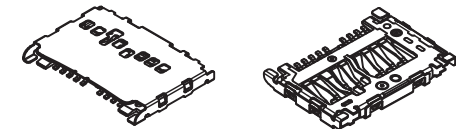
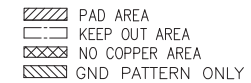


NOTE:

- Material:
 - Housing:High Temperature Thermoplastic, (LCP S475)Color Black UL 94V-0.
 - Contact: Phosphor Bronze(C5210R-SH T=0.12mm)
 - Cover: SUS304-H T=0.10mm
- Plating:
 - Contact terminal:
Contact area: Gold 2u" Min.Middle Pd-Ni 8u" min.
Solder area: Gold 1u" Min.
Underplating: Ni overall 80U" Min.
 - Cover:
Underplating: Ni overall 30U" Min.
Solder area: Gold 1u" Min.
- Specification:
 - Contact Current Rating:0.5Amperes.
 - Dielectric Withstanding Voltage:AC500V r.m.s.
 - Insulation Resistance:1000 Megohms Minimum At DC 500V.
 - Contact Resistance:100 mΩ Maximum.
 - Mating Cycles:5,000 Cycles.
 - Operating Temperature:-25°C~+60°C.
- Product Compliant to RoHS Directive 2002/95/EC and ELV 2000/53/EC
- Part Must Comply Taisol HF WD-3-I-091 Specification.
- Recommending A Metal More Than 0.15mm Thick.
Please Confirm Solderability, If Use A Metal Mask Less Than 0.15mm Thick.



RECOMMEND P.C.B LAYOUT
(General tolerance ±0.05)



F	ER2209085	依客人要求修改长宽高公差至+/-0.15	FAJI	2022.09.14
E	ER2101004	前端凸出缩短0.3mm	Alexander	2020.12.19
D	ECN20190503002	电镀规格接触区域镀钌8u"+AU 2u"min, 焊脚:AU 1u"min 变更为接触去镀金AU 2u"min 焊脚AU 1u"min	janyz	2019.05.03
C	ECN20190305001	端子料带埋入塑胶, 增加底部塑胶强度	janyz	2019.03.05
REVISION NO.	ECR NO.	DESCRIPTION	MARK	DATE

TITLE:
Micro SD H1.15 CARD CONN

PART NO.:
WHMS115-T7131-01

REMARK:

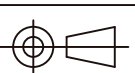
SIZE
A4

SACLE
1:1

SHEET
1/1

UNITS
MM[INCH]

REV
A0



GENERAL TOLERANCES
UNLESS SPECIFIED

x±0.35	x°±3.0°
.x±0.30	.x°±2.0°
.xx±0.25	.xx°±1.5°
.xxx±0.10	.xxx°±1.0°

APPROVED BY:
Geoffrey.Song

CHECKED BY:
Elvis.Song

DESIGND BY:
Sunny.Xu

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